



AOS Semiconductor Product Reliability Report

AOB11C60, rev A

Plastic Encapsulated Device

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This AOS product reliability report summarizes the qualification result for AOB11C60. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOB11C60 passes AOS quality and reliability requirements.

Table of Contents:

- I. Product Description
- II. Package and Die information
- III. Environmental Stress Test Summary and Result
- IV. Reliability Evaluation
- V. Appendix: Test data

I. Product Description:

The AOB11C60 is fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications. By providing low RDS(on), Ciss and Crss along with guaranteed avalanche capability this parts can be adopted quickly into new and existing offline power supply designs.

For Halogen Free add "L" suffix to part number:
 AOB11C60L

Details refer to the datasheet.

II. Die / Package Information:

	AOB11C60
Process	Standard sub-micron 600V N-Channel MOSFET
Package Type	TO263
Lead Frame	Bare Cu
Die Attach	Soft solder
Bonding	Al wire
Mold Material	Epoxy resin with silica filler
Moisture Level	Up to Level 1 *
Note * based on info provided by assembler and mold compound supplier	

III. Result of Reliability Stress for AOB11C60

Test Item	Test Condition	Time Point	Lot Attribution	Total Sample size	Number of Failures	Reference Standard
MSL Precondition	168hr 85°C /85%RH +3 cycle reflow @250°C	-	12 lots	2112pcs	0	JESD22-A113
HTGB	Temp = 150°C , Vgs=100% of Vgsmax	168hrs 500 hrs 1000 hrs	3 lots 4 lots	539pcs 77 pcs / lot	0	JESD22-A108
HTRB	Temp = 150°C , Vds=80% of Vdsmax	168hrs 500 hrs 1000 hrs	3 lots 4 lots	539pcs 77 pcs / lot	0	JESD22-A108
HAST	130°C , 85%RH, 33.3 psi, Vgs = 100% of Vgs max	96 hrs	9 lots (Note A*)	495pcs 55 pcs / lot	0	JESD22-A110
Pressure Pot	121°C , 29.7psi, RH=100%	96 hrs	9 lots (Note A*)	693pcs 77 pcs / lot	0	JESD22-A102
Temperature Cycle	-65°C to 150°C , air to air,	250 / 500 cycles	12 lots (Note A*)	924pcs 77 pcs / lot	0	JESD22-A104

IV. Reliability Evaluation

FIT rate (per billion): 4.16

MTTF = 27426 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the selected product (AOB11C60). Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

$$\text{Failure Rate (FIT)} = \text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)]$$

$$= 1.83 \times 10^9 / [2 \times (6 \times 77 \times 500 + 8 \times 77 \times 1000) \times 259] = 4.16$$

$$\text{MTTF} = 10^9 / \text{FIT} = 2.40 \times 10^8 \text{hrs} = 27426 \text{ years}$$

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from HTRB and HTGB tests

H = Duration of HTRB/HTGB testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [Af] = $\text{Exp} [E_a / k (1/T_j u - 1/T_j s)]$

Acceleration Factor ratio list:

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	259	87	32	13	5.64	2.59	1

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u = The use junction temperature in degree (Kelvin), K = C+273.16

k = Boltzmann's constant, 8.617164 x 10⁻⁵eV / K